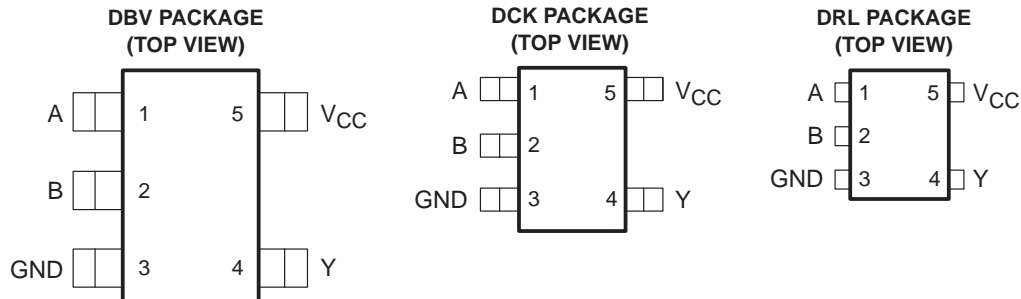


SN74AHC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

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- Operating Range of 2 V to 5.5 V
- Max t_{pd} of 8 ns at 5 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 8 -mA Output Drive at 5 V
- Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

description/ordering information

The SN74AHC1G86 is a single 2-input exclusive-OR gate. The device performs the Boolean function $Y = A \oplus B$ or $Y = \bar{A}B + A\bar{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
–40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G86DBVR	A86_
		Reel of 250	SN74AHC1G86DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G86DCKR	AH_
		Reel of 250	SN74AHC1G86DCKT	
	SOT (SOT-553) – DRL	Reel of 4000	SN74AHC1G86DRLR	AH_

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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 **TEXAS
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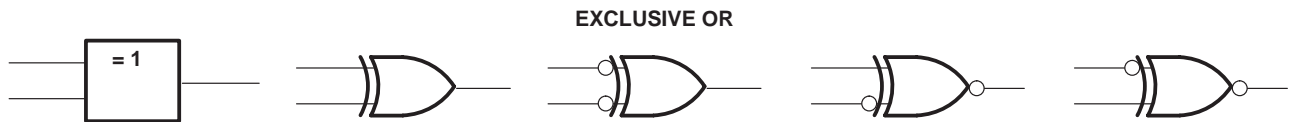
SN74AHC1G86

SINGLE 2-INPUT EXCLUSIVE-OR GATE

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exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an SN74AHC1G86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



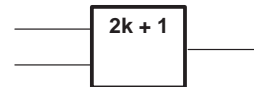
The output is active (low) if all inputs stand at the same logic level (i.e., $A = B$).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
..... DCK package	252°C/W
..... DRL package	142°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN74AHC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

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recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5	V
		V _{CC} = 3 V	2.1	
		V _{CC} = 5.5 V	3.85	
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5	V
		V _{CC} = 3 V	0.9	
		V _{CC} = 5.5 V	1.65	
V _I	Input voltage	0	5.5	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V	-50	μA
		V _{CC} = 3.3 V ± 0.3 V	-4	
		V _{CC} = 5 V ± 0.5 V	-8	
I _{OL}	Low-level output current	V _{CC} = 2 V	50	μA
		V _{CC} = 3.3 V ± 0.3 V	4	
		V _{CC} = 5 V ± 0.5 V	8	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V	100	ns/V
		V _{CC} = 5 V ± 0.5 V	20	
T _A	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V _{OH}	I _{OH} = -50 μA	2 V	1.9	2	1.9	V		
		3 V	2.9	3	2.9			
		4.5 V	4.4	4.5	4.4			
	I _{OH} = -4 mA	3 V	2.58		2.48			
	I _{OH} = -8 mA	4.5 V	3.94		3.8			
V _{OL}	I _{OL} = 50 μA	2 V			0.1	0.1	V	
		3 V			0.1	0.1		
		4.5 V			0.1	0.1		
	I _{OL} = 4 mA	3 V			0.36	0.44		
	I _{OL} = 8 mA	4.5 V			0.36	0.44		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	±1	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			1	10	μA	
C _i	V _I = V _{CC} or GND	5 V		4	10	10	pF	



SN74AHC1G86

SINGLE 2-INPUT EXCLUSIVE-OR GATE

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
t_{PLH}	A or B	Y	$C_L = 15\text{ pF}$	7	11	1	13	ns	
t_{PHL}				7	11	1	13		
t_{PLH}	A or B	Y	$C_L = 50\text{ pF}$	9.5	14.5	1	16.5	ns	
t_{PHL}				9.5	14.5	1	16.5		

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

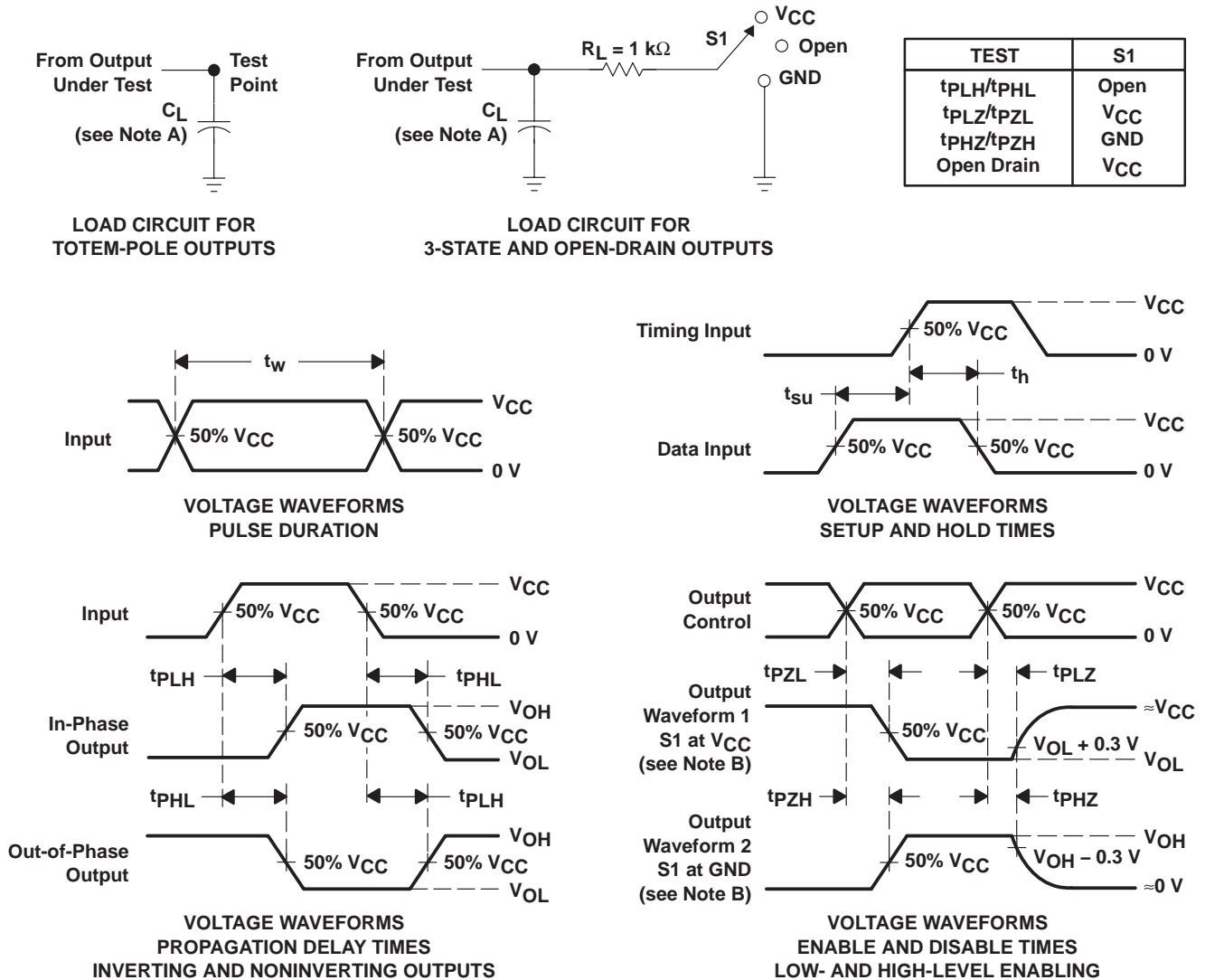
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
t_{PLH}	A or B	Y	$C_L = 15\text{ pF}$	4.8	6.8	1	8	ns	
t_{PHL}				4.8	6.8	1	8		
t_{PLH}	A or B	Y	$C_L = 50\text{ pF}$	6.3	8.8	1	10	ns	
t_{PHL}				6.3	8.8	1	10		

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	18	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50\ \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC1G86DBVG4	ACTIVE	SOT-23	DBV	5		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC1G86DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(A862 ~ A863 ~ A86G ~ A86J ~ A86S)	Samples
SN74AHC1G86DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(A862 ~ A863 ~ A86G ~ A86J ~ A86S)	Samples
SN74AHC1G86DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(A862 ~ A863 ~ A86G ~ A86J ~ A86S)	Samples
SN74AHC1G86DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(A862 ~ A863 ~ A86G ~ A86S)	Samples
SN74AHC1G86DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(AH3 ~ AHG ~ AHJ ~ AHS)	Samples
SN74AHC1G86DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(AH3 ~ AHG ~ AHJ ~ AHS)	Samples
SN74AHC1G86DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(AH3 ~ AHG ~ AHJ ~ AHS)	Samples
SN74AHC1G86DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(AH3 ~ AHG ~ AHS)	Samples
SN74AHC1G86DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(AH3 ~ AHG ~ AHS)	Samples
SN74AHC1G86DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHS	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AHC1G86 :

● Automotive: [SN74AHC1G86-Q1](#)

● Enhanced Product: [SN74AHC1G86-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G86DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74AHC1G86DBVT	SOT-23	DBV	5	250	178.0	9.2	3.3	3.2	1.55	4.0	8.0	Q3
SN74AHC1G86DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74AHC1G86DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G86DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AHC1G86DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHC1G86DRLR	SOT	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

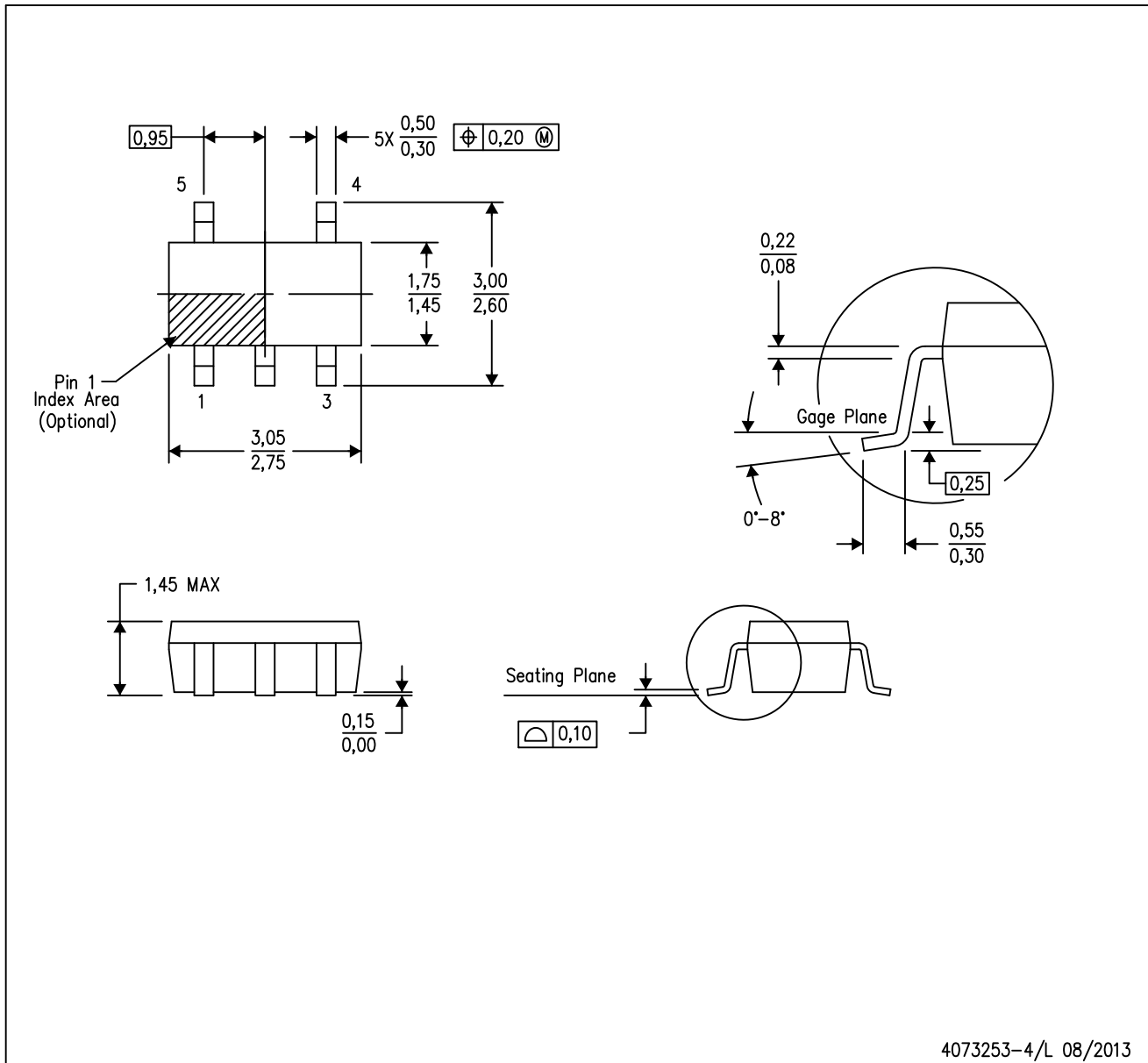

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G86DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74AHC1G86DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHC1G86DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74AHC1G86DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHC1G86DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74AHC1G86DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74AHC1G86DRLR	SOT	DRL	5	4000	202.0	201.0	28.0

MECHANICAL DATA

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4073253-4/L 08/2013

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

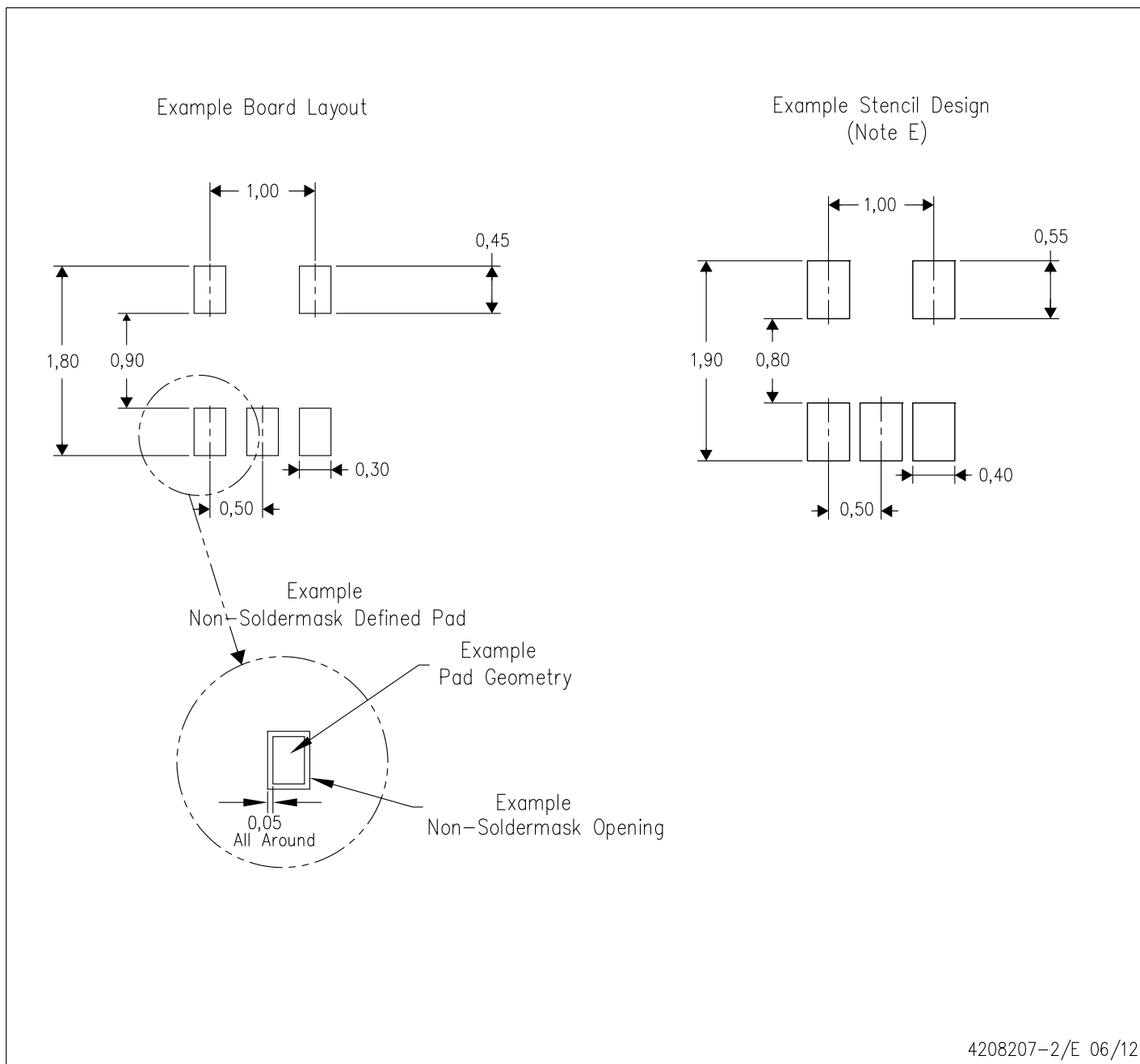
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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